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(12)

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Maeda et al.

(10)

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(45)

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(54) **EARPHONE**

(71) Applicant: **JVC KENWOOD Corporation,**
Yokohama (JP)

(72) Inventors: **Takaaki Maeda,** Yokohama (JP);
Satoshi Yoshimura, Yokohama (JP);
Jeong-ju Choe, Yokohama (JP)

(73) Assignee: **JVC KENWOOD CORPORATION,**
Yokohama (JP)

(**) Term: **15 Years**

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(52) **U.S. Cl.**
USPC **D14/223**

(58) **Field of Classification Search**
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455/575.1, 569.1
CPC H04R 1/10; H04R 25/00; H04R 1/1016;
H04R 1/1066; H04R 5/033; H04R
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See application file for complete search history.

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Primary Examiner — Paula Allen Greene
(74) *Attorney, Agent, or Firm* — Nath, Goldberg &
Meyer; Jerald L. Meyer

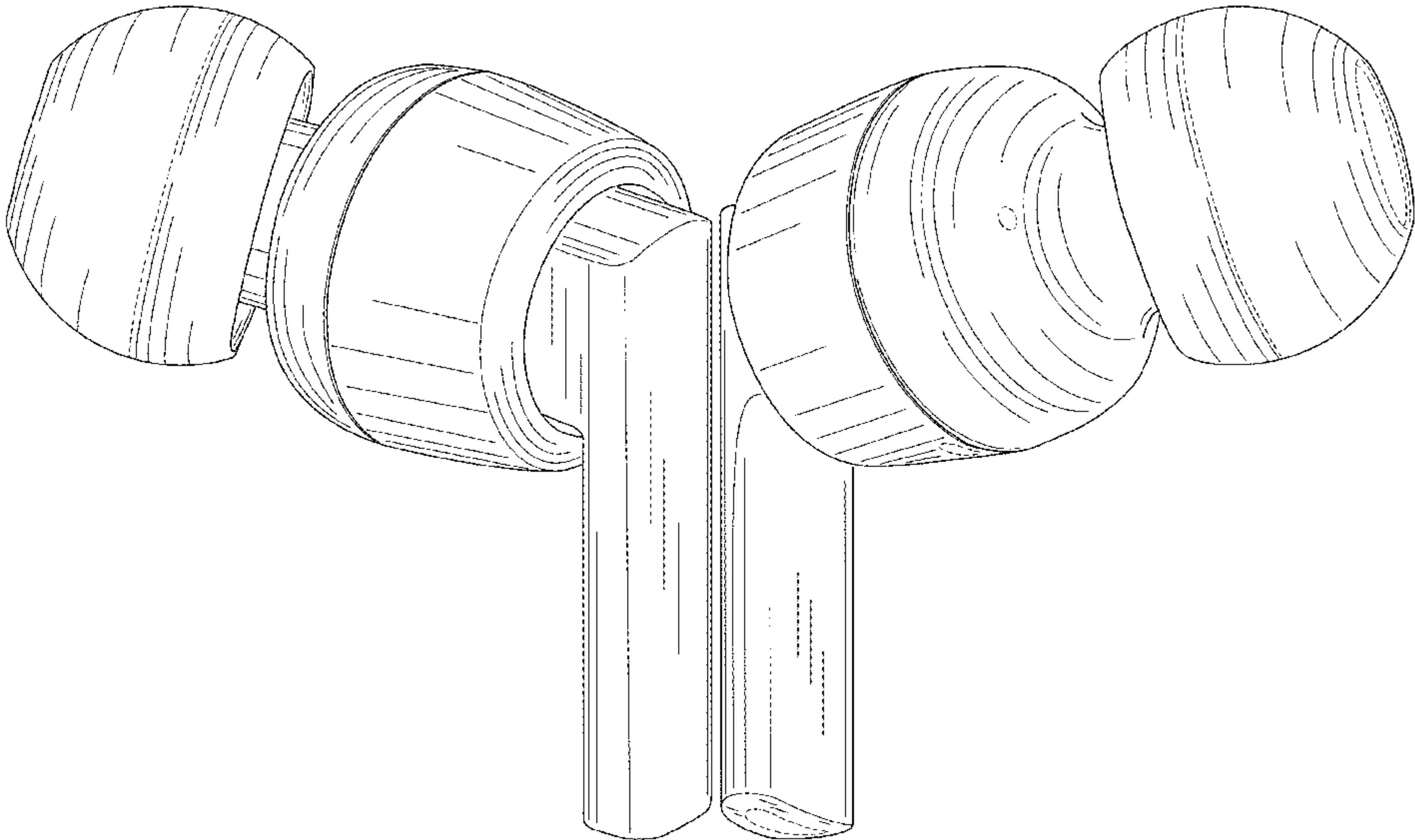
(57) **CLAIM**

The ornamental design for an earphone, as shown and described.

DESCRIPTION

FIG. 1 is a front perspective view of an earphone, FIG. 2 is a rear perspective view thereof, FIG. 3 is a front elevational view thereof, FIG. 4 is a rear elevational view thereof, FIG. 5 is a top plan view thereof, FIG. 6 is a bottom plan view thereof, FIG. 7 is a left side elevational view thereof; and, FIG. 8 is a right side elevational view thereof. The broken lines immediately adjacent the shaded areas represent the bounds of the claimed design while all other broken lines are directed to environment that are for illustrative purposes only The broken lines form no part of the claimed design.

1 Claim, 8 Drawing Sheets



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Fig.1

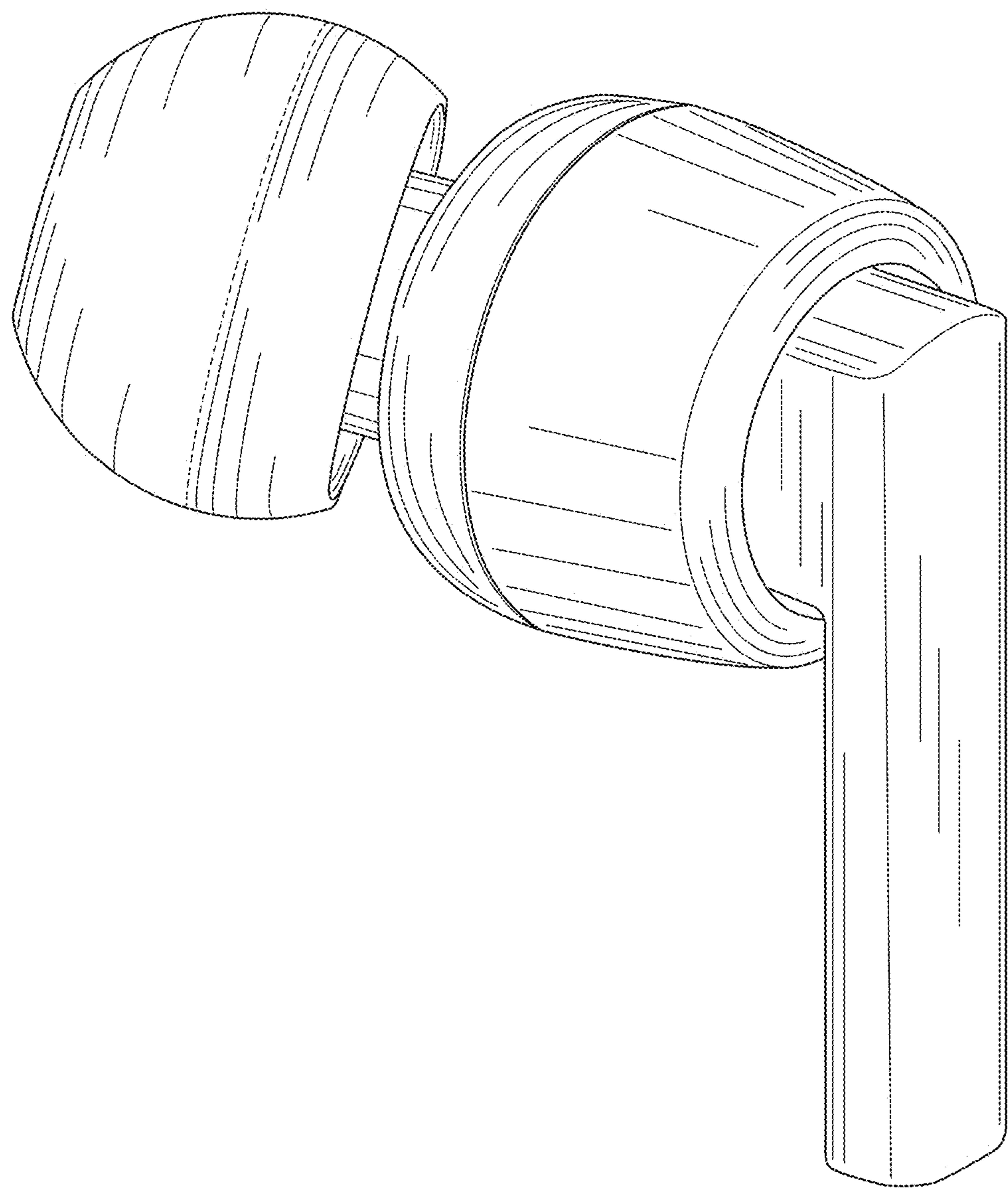


Fig.2

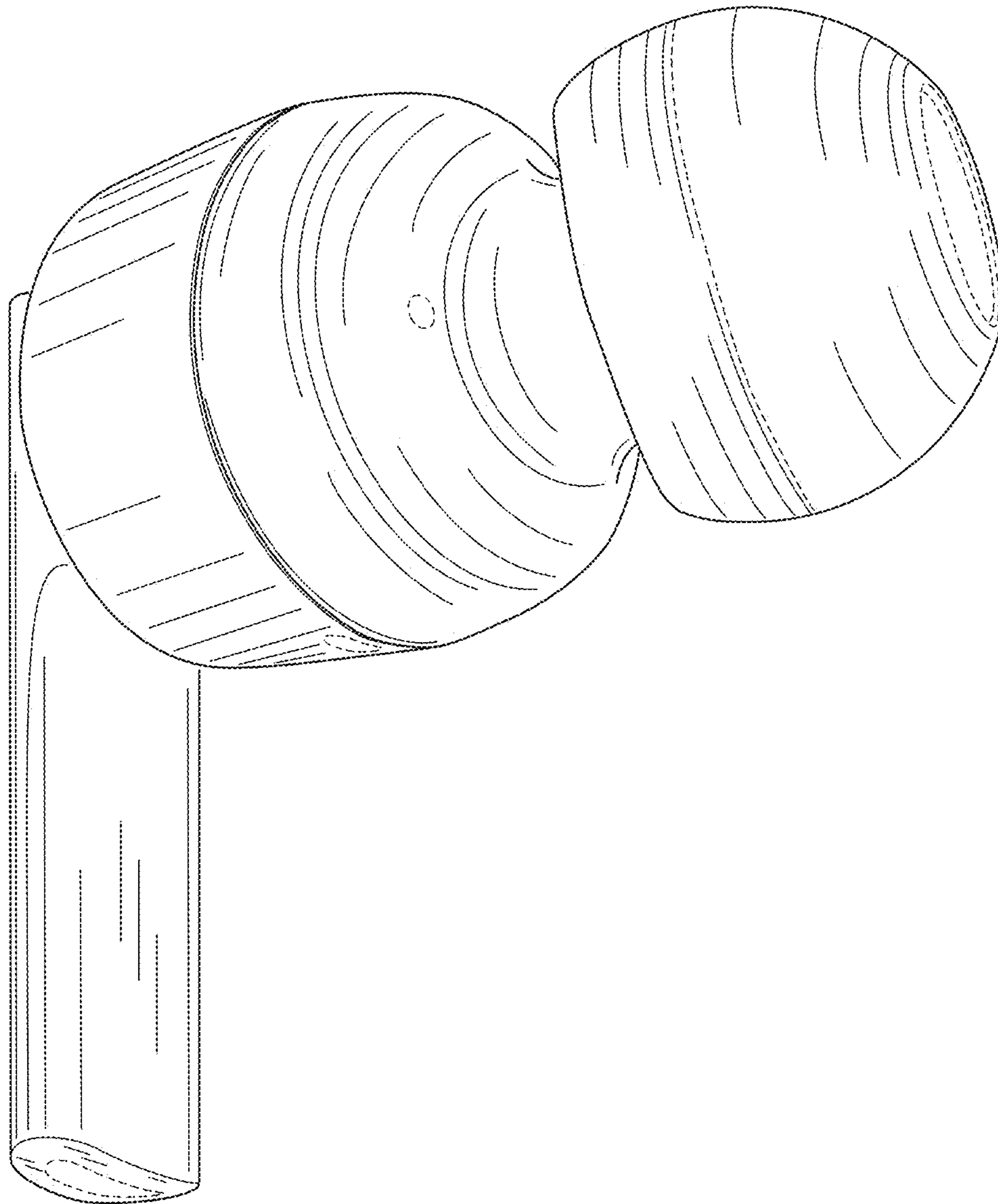


Fig.3

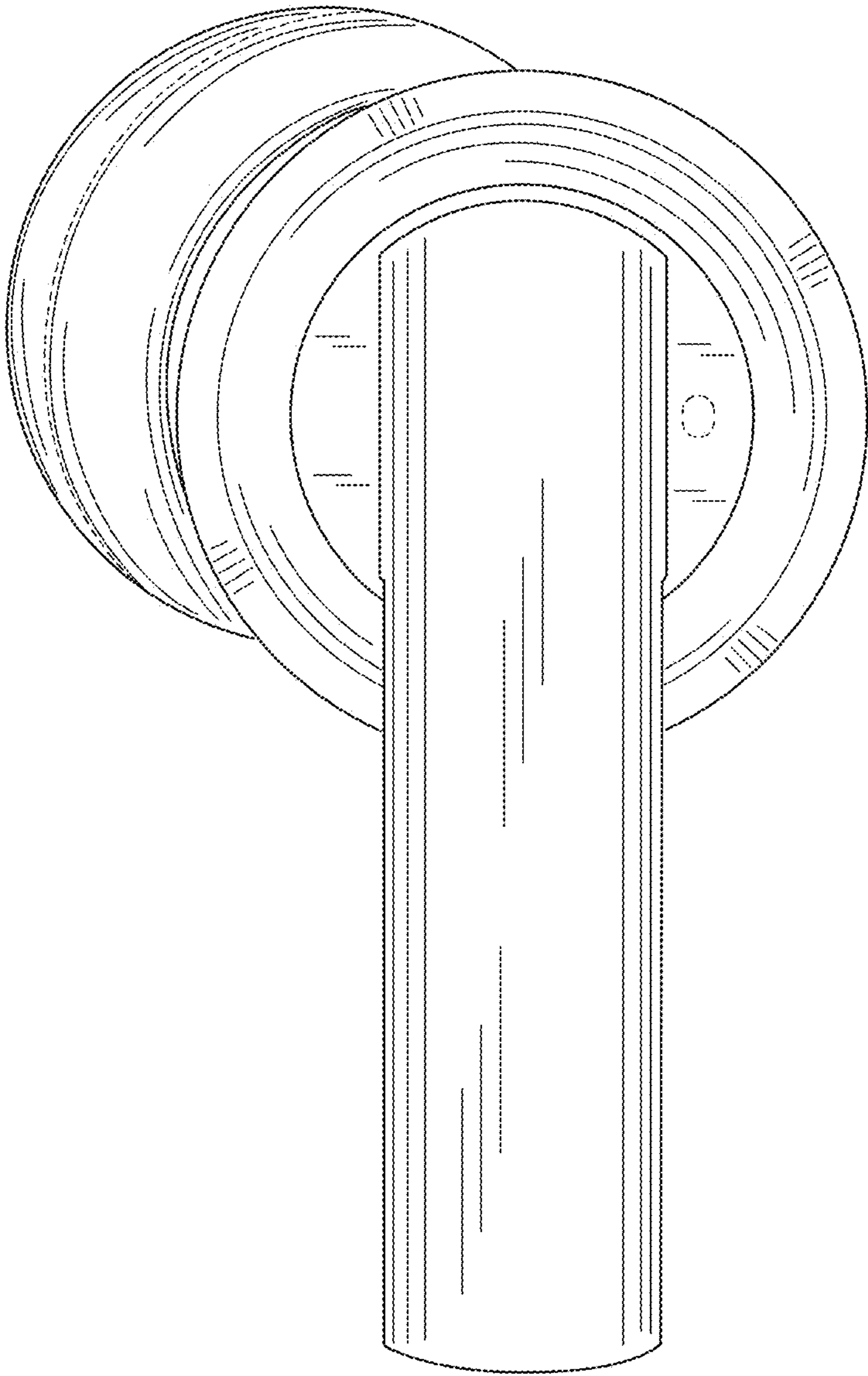


Fig.4

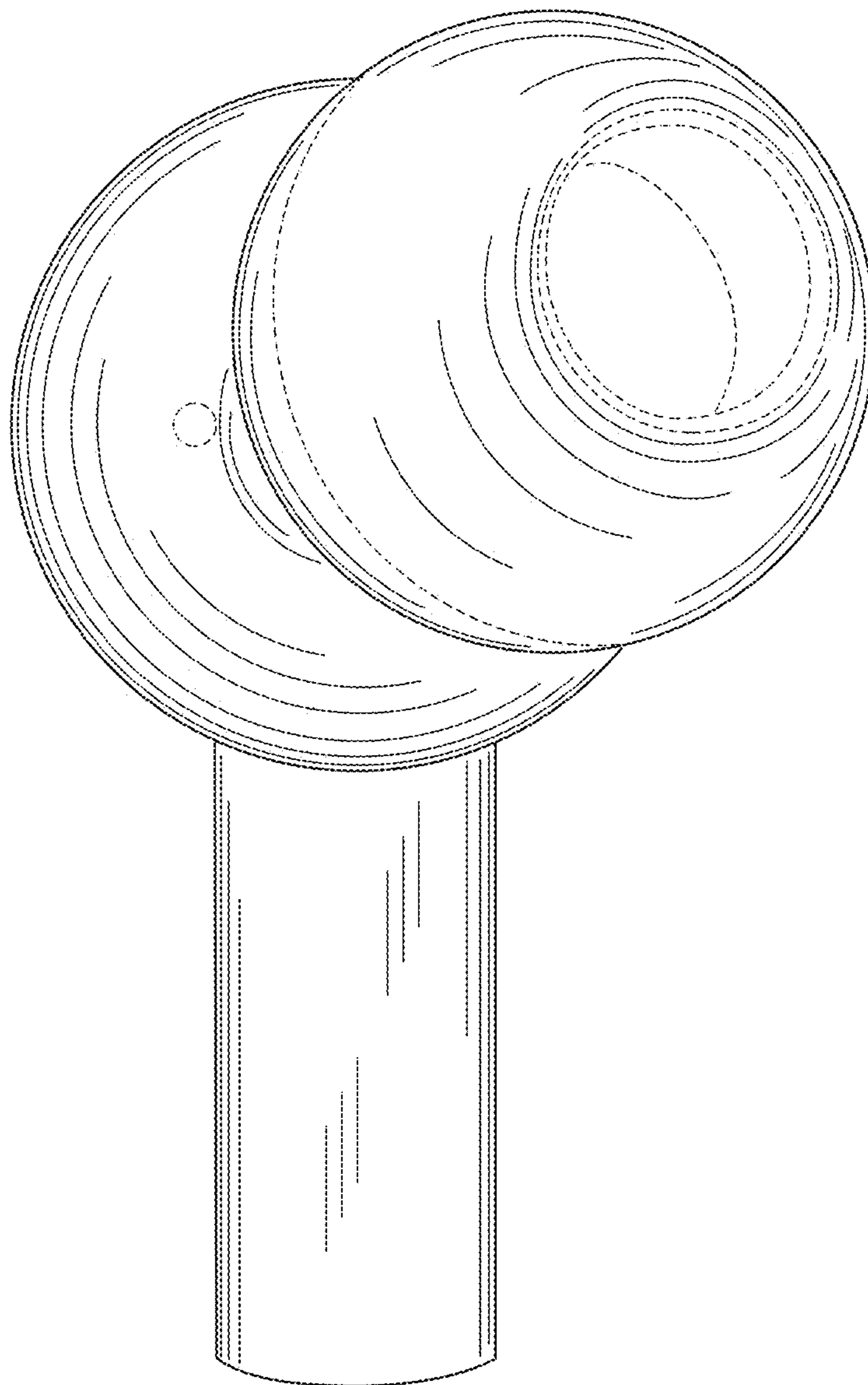


Fig.5

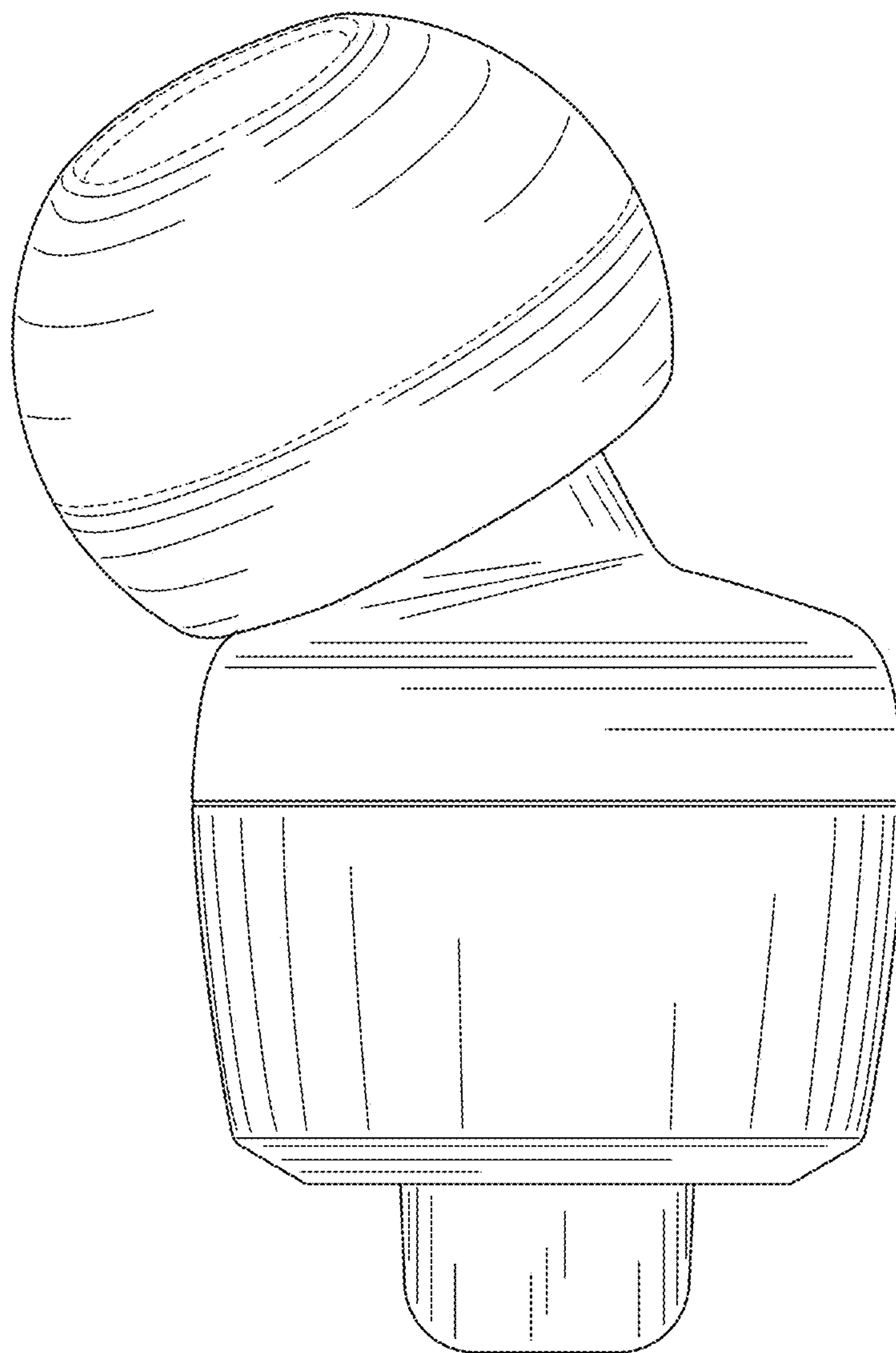


Fig.6

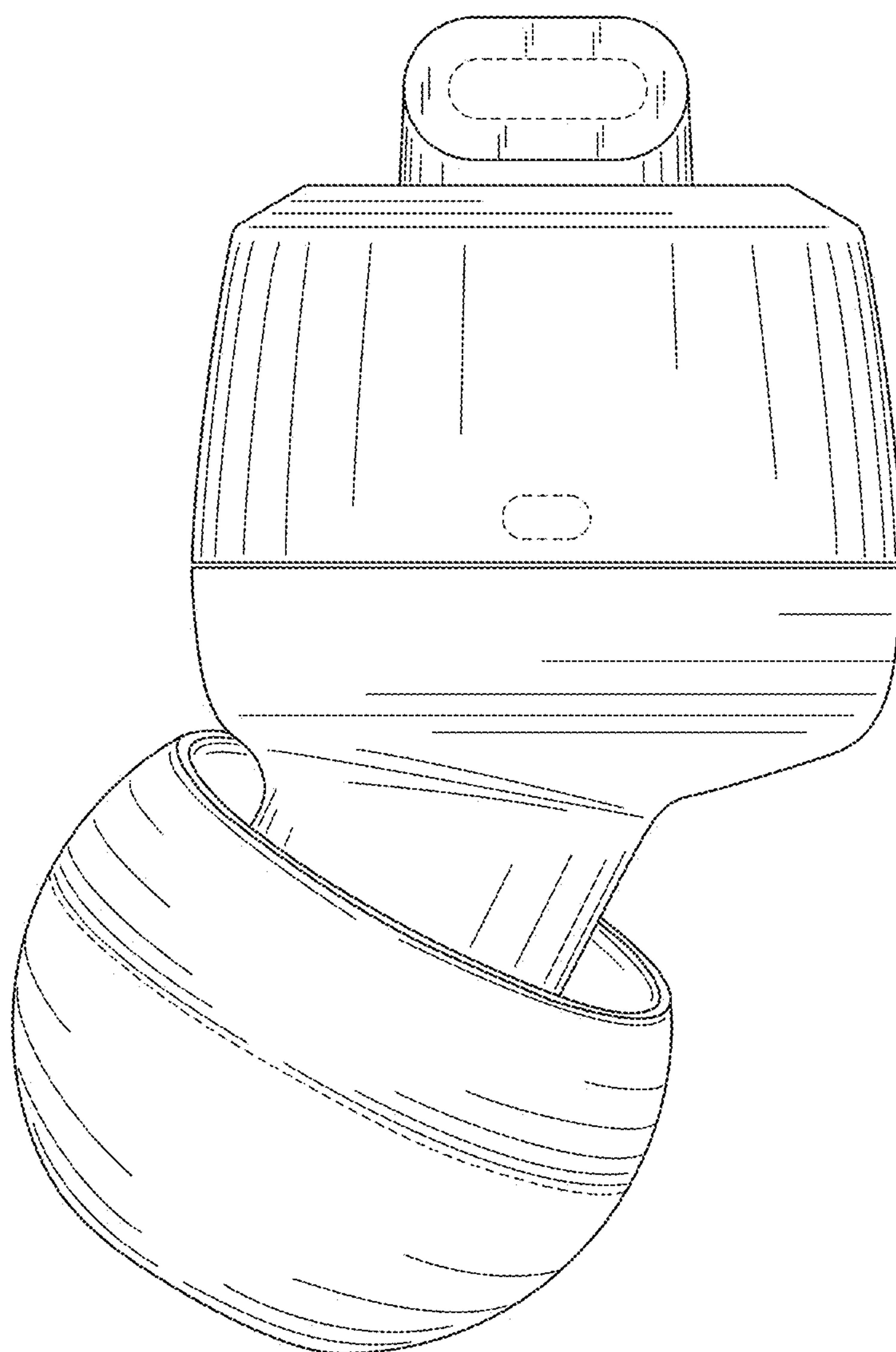


Fig.7

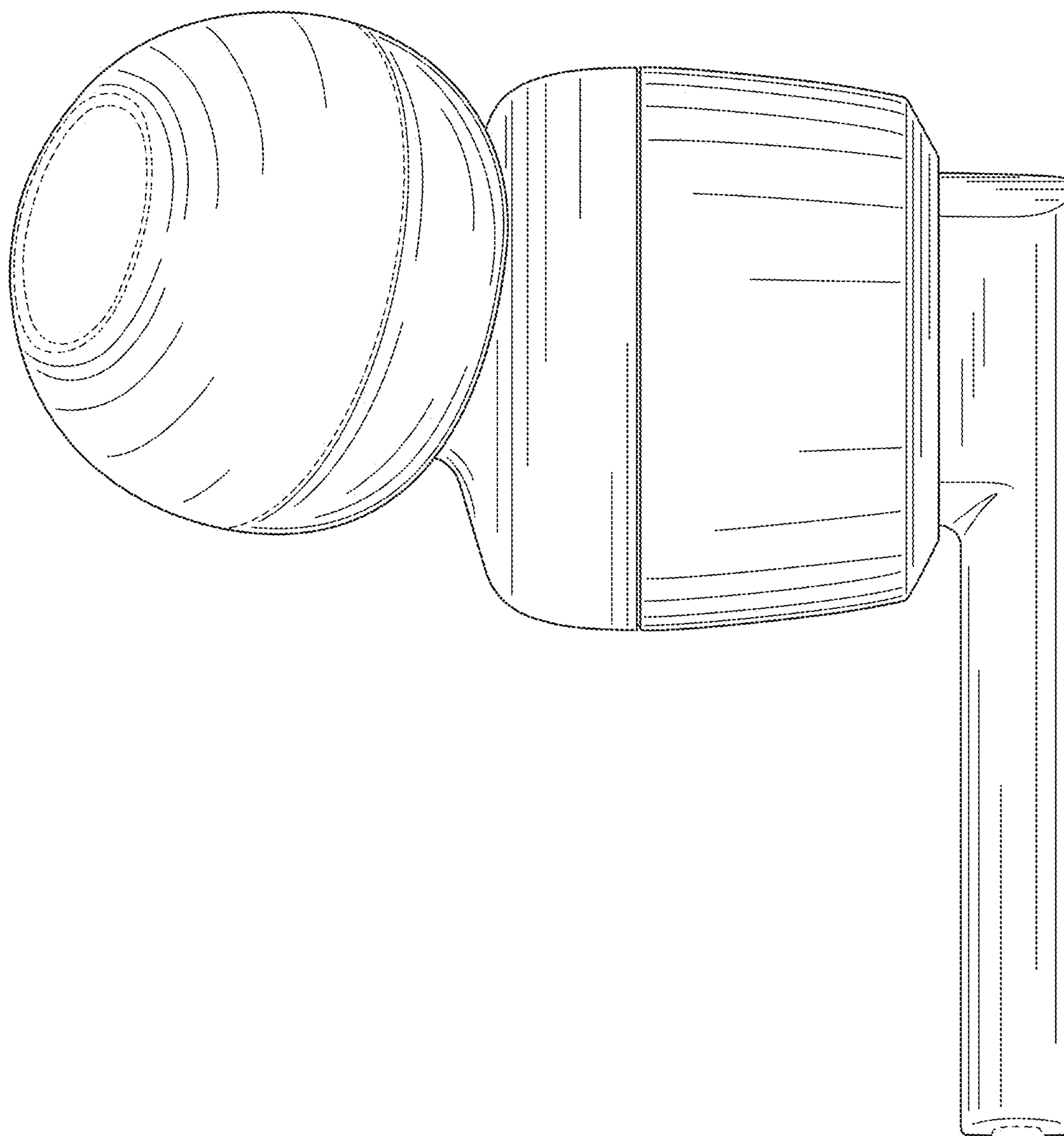


Fig.8

